

Global Through-Silicon Vias (TSVs) Market 2024 by Company, Regions, Type and Application, Forecast to 2030

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Abstracts

According to our (Global Info Research) latest study, the global Through-Silicon Vias (TSVs) market size was valued at US\$ 2974 million in 2023 and is forecast to a readjusted size of USD 7994 million by 2030 with a CAGR of 14.2% during review period.

Silicon through-hole Technology (TSV) is a kind of circuit interconnection technology. It realizes interconnection between chips by making vertical conduction between chips and between wafers and between wafers. Different from the previous IC packaging bonding and dot coating stacking technology, TSV can maximize the chip stacking density in three-dimensional direction, reduce the chip size, increase the transistor density of the chip, improve the electrical interconnection performance between layers, improve the chip operation speed, and reduce the power consumption, design difficulty and cost of the chip.

At the regional level, Through-Silicon Vias (TSVs) products are mainly sold in North America, Europe and China, among which China accounts for about 25% of the global market. Currently, major global suppliers include ASE Technology Holding, Amkor Technology, Taiwan Semiconductor Manufacturing Company Limited, Intel Corporation, GLOBALFOUNDRIES, JCET Group, Samsung, Tianshui Huatian Technology, etc. These major enterprises account for more than 80% of the total share.

The global Through-Silicon Vias (TSVs) market is poised for significant growth due to the rising demand for high-performance, compact, and energy-efficient electronic devices. TSV technology is a critical enabler of 3D integrated circuits (ICs) and advanced packaging solutions, making it essential for applications like artificial intelligence (AI), 5G, automotive electronics, and high-performance computing (HPC).

Market Growth Drivers

Demand for 3D Integration:

TSVs enable vertical stacking of chips, reducing the interconnect length and enhancing performance, making them indispensable for 3D ICs and heterogeneous integration. Applications in logic-memory integration, MEMS, and CMOS image sensors are key contributors.

Proliferation of AI and 5G:

TSVs are critical for high-bandwidth memory (HBM), used in AI accelerators and 5G base stations.

These technologies require higher data transfer rates, lower latency, and reduced power consumption, driving TSV adoption.

Miniaturization and High-Density Packaging:

The trend towards smaller, lighter, and more functional devices necessitates the use of TSVs for high-density interconnects.

Growth in Automotive Electronics:

The demand for advanced driver-assistance systems (ADAS), autonomous driving, and in-vehicle sensors is spurring the adoption of TSV-enabled components.

Expansion in Data Centers and HPC:

High-performance TSV-based packaging solutions are essential for the increasing processing power demands in cloud computing and data centers.

This report is a detailed and comprehensive analysis for global Through-Silicon Vias (TSVs) market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2024, are provided.

Key Features:

Global Through-Silicon Vias (TSVs) market size and forecasts, in consumption value (\$ Million), 2019-2030

Global Through-Silicon Vias (TSVs) market size and forecasts by region and country, in consumption value (\$ Million), 2019-2030

Global Through-Silicon Vias (TSVs) market size and forecasts, by Type and by Application, in consumption value (\$ Million), 2019-2030

Global Through-Silicon Vias (TSVs) market shares of main players, in revenue (\$ Million), 2019-2024

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Through-Silicon Vias (TSVs)

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Through-Silicon Vias (TSVs) market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include ASE Technology Holding, Amkor Technology, TSMC, Intel, GlobalFoundries, JCET Group, Samsung, HT-tech, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

Through-Silicon Vias (TSVs) market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

- 2.5D TSV
- 3D TSV

Market segment by Application

- Mobile and Consumer Electronics
- Communication Equipment
- Automotive Electronics
- Other

Market segment by players, this report covers

- ASE Technology Holding
- Amkor Technology
- TSMC
- Intel
- GlobalFoundries
- JCET Group
- Samsung

- HT-tech

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe Through-Silicon Vias (TSVs) product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of Through-Silicon Vias (TSVs), with revenue, gross margin, and global market share of Through-Silicon Vias (TSVs) from 2019 to 2024.

Chapter 3, the Through-Silicon Vias (TSVs) competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and by Application, with consumption value and growth rate by Type, by Application, from 2019 to 2030.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2019 to 2024. and Through-Silicon Vias (TSVs) market forecast, by regions, by Type and by Application, with consumption value, from 2025 to 2030.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of Through-Silicon Vias (TSVs).

Chapter 13, to describe Through-Silicon Vias (TSVs) research findings and conclusion.

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